



Contactless Leadframe

Metal stamped design optimized for contactless card applications

Linxens Contactless Leadframe (LOA2 / LOA4) is compatible with the standard mass market (OA2/OA4) industry design. Compliant with ISO standards, the Leadframe is **manufactured** together with a chip that is designed for contactless cards for Financial services, Government, Transport, Access Control markets.

- Stamped copper with silver plating. Available in two different copper metal thicknesses, LOA4 **producing** the thinnest module size of 250µm. Linxens' unique selective plating solution allow reduction of silver plating area so overall cost optimization.
- Delivered in standard 35mm reel allowing module manufacturers to reuse the existing molding equipment for chip assembly. For card manufacturers, it enables full compatibility with the inlay production equipment.

Part Number	Designation	Die Pad Size class	Thickness class	Plating*
9X90002AA	Leadframe LOA2	3.4mm x 3.7mm	80µm	two-sided strip plating
9X90002BA	Leadframe LOA4	3.4mm x 3.7mm	60µm	two-sided strip plating

*Contact Linxens to request for plating options with product specifications.

- Linxens' proprietary stamping and plating technology allow customize product design of leadframes that can be used for other applications based on customer demand.
- Linxens offers chip module assembly on Contactless Leadframes. The Module Packaging Services datasheet will provide further information.

Feel free to contact Linxens for any requests for tailored-made solutions in order to meet specific requirements.



SPECIALTY



Module Configurations

Material

- Material n° DIN EN CW452K
- Alloy CuSn6
- Hardness HV 180-230
- Thickness 0.06mm / 0.08mm
- Tolerance: ± 0.005 mm

Specifications

- Reel-to-reel format
- 35mm film
- Pitch 9.5 mm

Plating

- Min 1µm Ni all over
- Min 1.5µm Ag in selective plating area

Thickness

- Overall plating included:
- LOA2 0.082 +0.007 / -0.005mm
 - LOA4 0.062 +0.007 / -0.005mm

International Standards

- ISO/IEC 7810
- ISO/IEC 7816-1
- ISO/IEC 10373-1 and 10373-3
- MIL Std 883

Application Area

- Contactless chip card
- Government
- Transport
- Access control
- Financial services